

# BIPOLAR ANALOG INTEGRATED CIRCUIT

# $\mu$ PC4556

## HIGH PERFORMANCE DUAL DECOMPENSATED OPERATIONAL AMPLIFIER

### DESCRIPTION

The  $\mu$ PC4556 is a dual operational amplifier which features further advanced A.C. performance than that of the  $\mu$ PC4558. Decompensation characteristic guarantees 20MHz gain-bandwidth product higher than 20 dB. Also featured are low input noise and high output drive capability making this device the optimum choice for audio application.

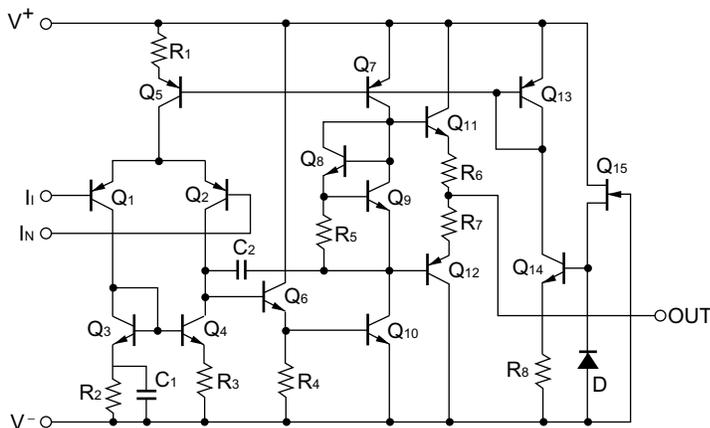
### FEATURES

- Gain bandwidth products: 20 MHz ( $A_v \geq 20$  dB)
- High slew rate: 5 V/ $\mu$ s
- Low input noise voltage: 6  $\mu$ V<sub>p-p</sub>
- Internal frequency compensation ( $A_v \geq 20$  dB)

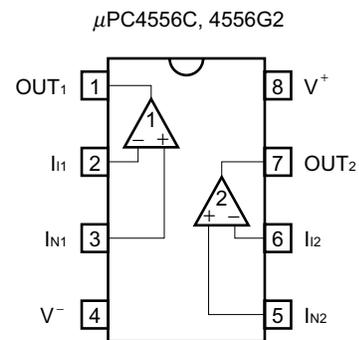
### ★ ORDERING INFORMATION

Part Number	Package
$\mu$ PC4556C	8-pin plastic DIP (7.62 mm (300))
$\mu$ PC4556G2	8-pin plastic SOP (5.72 mm (225))

### EQUIVALENT CIRCUIT



### PIN CONFIGURATION (Top View)



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 Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C)**

Parameter		Symbol	Ratings	Unit
Voltage between V <sup>+</sup> and V <sup>-</sup> <sup>Note 1</sup>		V <sup>+</sup> - V <sup>-</sup>	-0.3 to +36	V
Differential Input Voltage		V <sub>ID</sub>	±30	V
Input Voltage <sup>Note 2</sup>		V <sub>I</sub>	V <sup>-</sup> -0.3 to V <sup>+</sup> +0.3	V
Output Voltage <sup>Note 3</sup>		V <sub>O</sub>	V <sup>-</sup> -0.3 to V <sup>+</sup> +0.3	V
Power Dissipation	C Package <sup>Note 4</sup>	P <sub>T</sub>	700	mW
	G2 Package <sup>Note 5</sup>		440	mW
Output Short Circuit Duration <sup>Note 6</sup>			Indefinite	sec
Operating Ambient Temperature		T <sub>A</sub>	-20 to +80	°C
Storage Temperature		T <sub>stg</sub>	-55 to +125	°C

- Notes**
- Reverse connection of supply voltage can cause destruction.
  - The input voltage should be allowed to input without damage or destruction. Even during the transition period of supply voltage, power on/off etc., this specification should be kept. The normal operation will establish when the both inputs are within the Common Mode Input Voltage Range of electrical characteristics.
  - This specification is the voltage which should be allowed to supply to the output terminal from external without damage or destructive. Even during the transition period of supply voltage, power on/off etc., this specification should be kept. The output voltage of normal operation will be the Output Voltage Swing of electrical characteristics.
  - Thermal derating factor is -7.0 mV/°C when operating ambient temperature is higher than 25°C.
  - Thermal derating factor is -4.4 mV/°C when operating ambient temperature is higher than 25°C.
  - Pay careful attention to the total power dissipation not to exceed the absolute maximum ratings, Note 4 and Note 5.

**RECOMMENDED OPERATING CONDITIONS**

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	V <sup>±</sup>	±4		±16	V

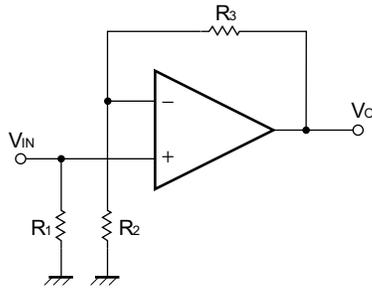
**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C, V<sup>±</sup> = ±15 V)**

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input Offset Voltage	V <sub>io</sub>	R <sub>s</sub> ≤ 10 kΩ		±0.5	±6	mV
Input Offset Current <sup>Note 7</sup>	I <sub>io</sub>			±5	±200	nA
Input Bias Current <sup>Note 7</sup>	I <sub>b</sub>			180	500	nA
Large Signal Voltage Gain	A <sub>v</sub>	R <sub>L</sub> ≥ 2 kΩ, V <sub>o</sub> = ±10 V	20000	100000		
Power Consumption	P <sub>d</sub>	I <sub>o</sub> = 0 A, Both Amplifiers		90	170	mW
Common Mode Rejection Ratio	CMR	R <sub>s</sub> ≤ 10 kΩ	70	90		dB
Supply Voltage Rejection Ratio	SVR	R <sub>s</sub> ≤ 10 kΩ		30	150	μV/V
Output Voltage Swing	V <sub>om</sub>	R <sub>L</sub> ≥ 2 kΩ	±12	±14		V
		I <sub>o</sub> = ±25 mA	±10	±11.5		V
Common Mode Input Voltage Range	V <sub>ICM</sub>		±12	±14		V
Slew Rate	SR	A <sub>v</sub> ≥ 10 (20 dB)		5		V/μs
Input Equivalent Noise Voltage	V <sub>n</sub>	R <sub>s</sub> = 1 kΩ, f = 1 Hz to 1 kHz		6		μV <sub>p-p</sub>
Channel Separation		f = 1 kHz		105		dB

**Notes 7.** Input bias currents flow out from IC. Because each currents are base current of PNP-transistor on input stage.

TYPICAL APPLICATION CIRCUIT

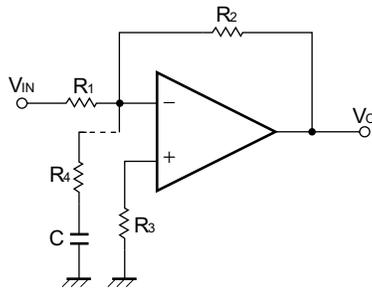
Noninverting Amplifier



$$R_3 \geq 9 \cdot R_2$$

$$R_1 = R_2$$

Inverting Amplifier



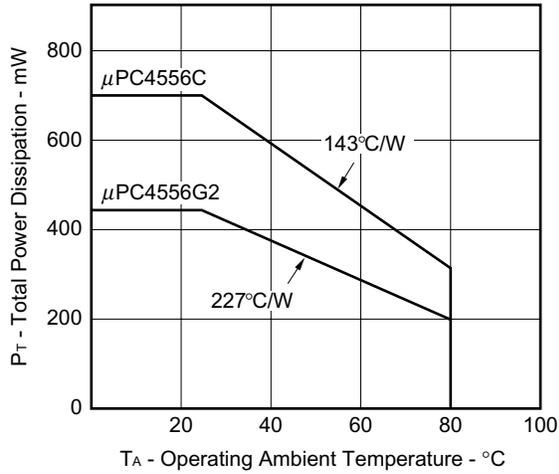
R<sub>4</sub>, C are necessary when R<sub>2</sub> < 10 · R<sub>1</sub>

$$R_4 \leq \frac{1}{9} R_2$$

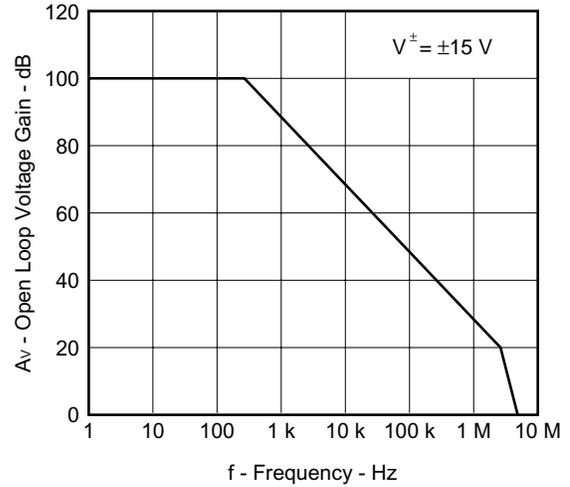
$$C \geq \frac{R_2/R_4}{2 \cdot \pi \cdot R_4 \cdot 5 \text{ MHz}}$$

TYPICAL PERFORMANCE CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ , TYP.)

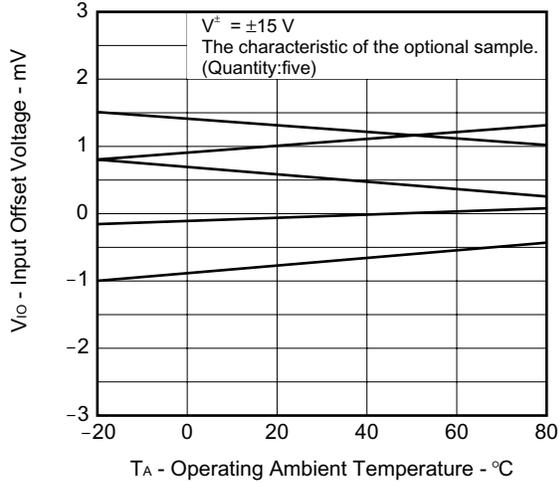
★ POWER DISSIPATION



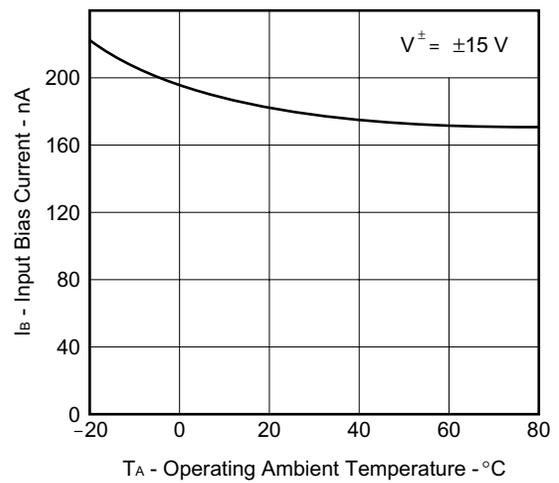
OPEN LOOP FREQUENCY RESPONSE



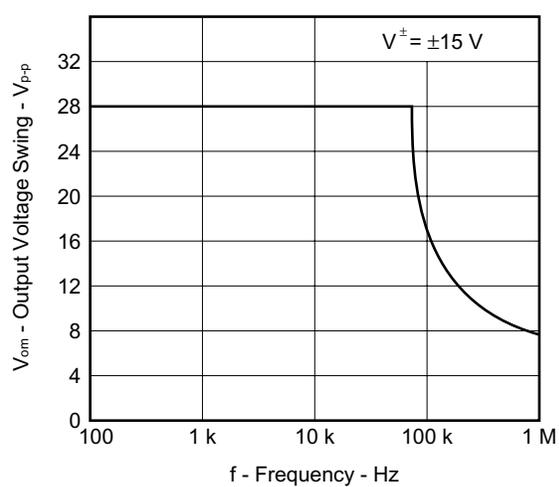
★ INPUT OFFSET VOLTAGE



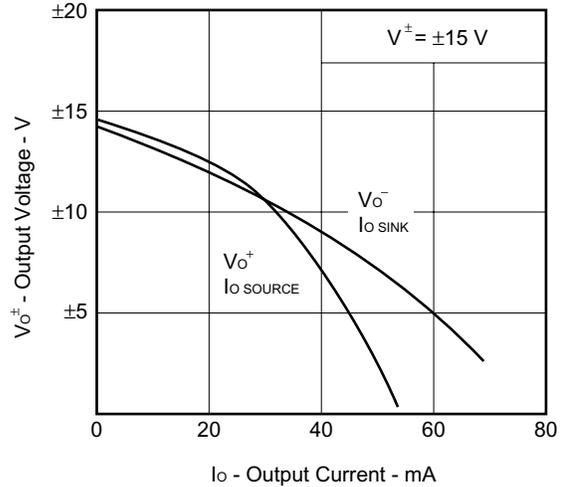
★ INPUT BIAS CURRENT

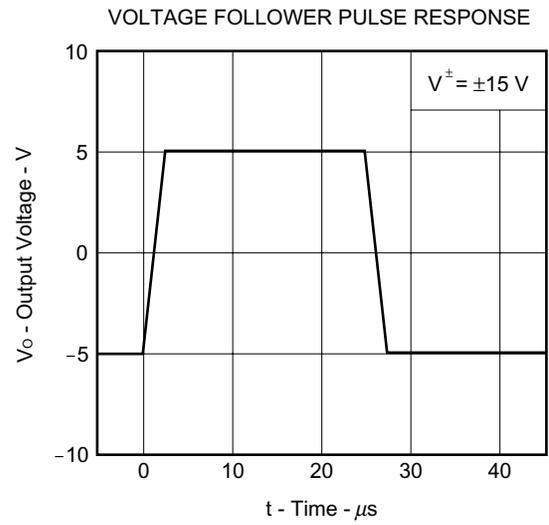
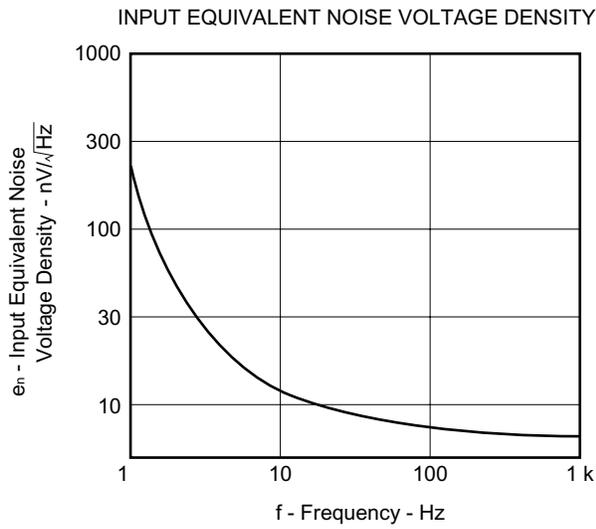
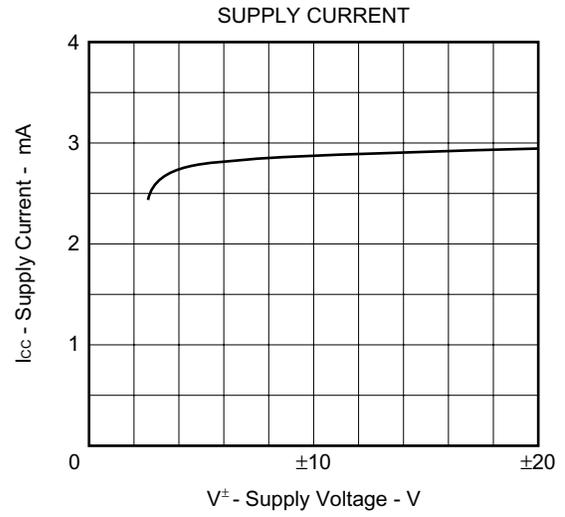
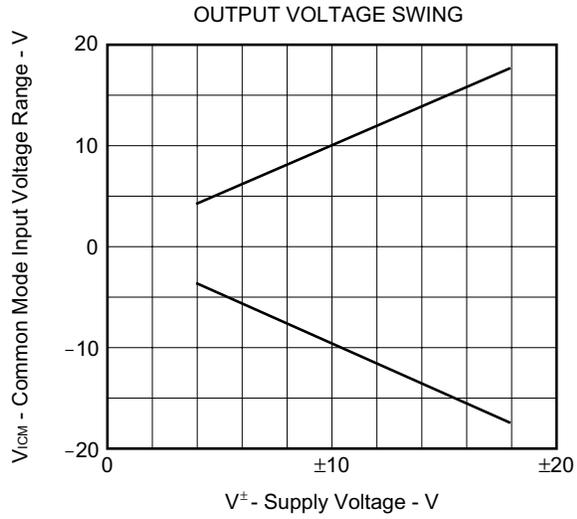


LARGE SIGNAL FREQUENCY RESPONSE



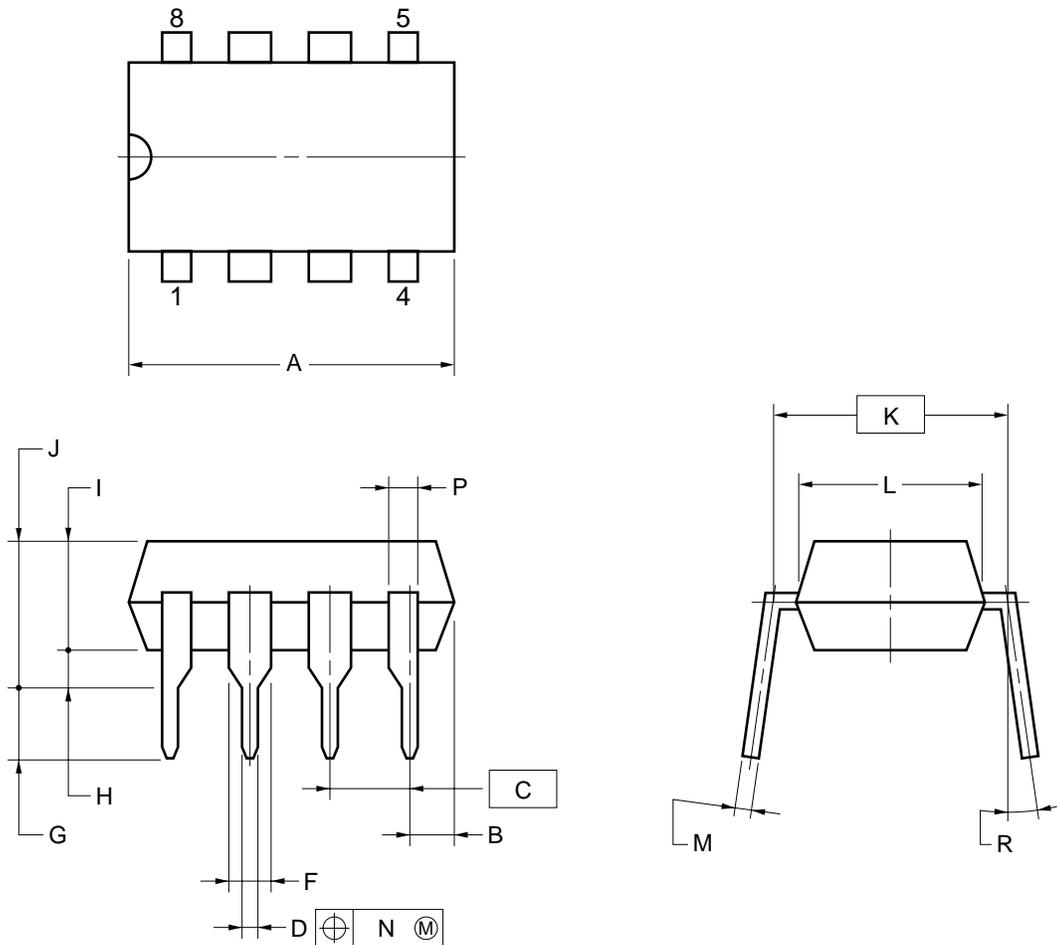
OUTPUT CURRENT LIMIT





★ PACKAGE DRAWINGS (Unit : mm)

8-PIN PLASTIC DIP (7.62mm(300))



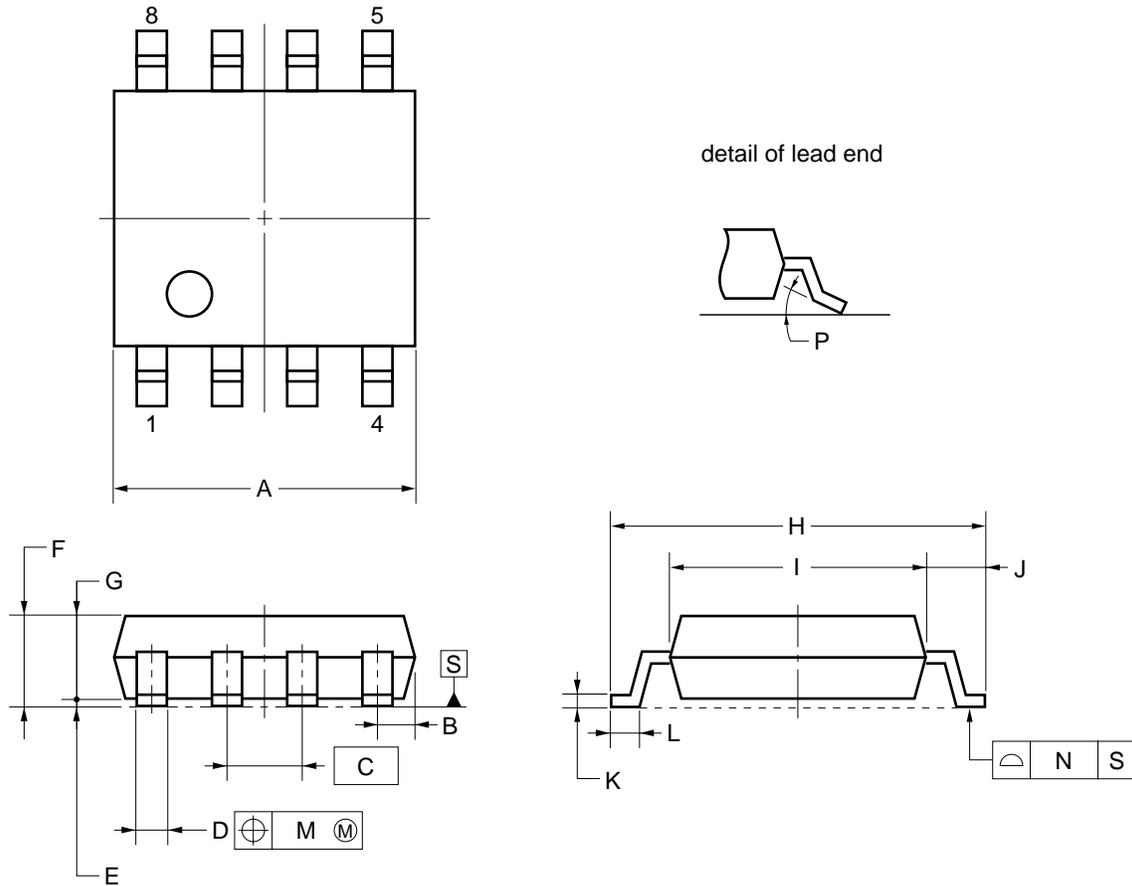
NOTES

1. Each lead centerline is located within 0.25 mm of its true position (T.P.) at maximum material condition.
2. Item "K" to center of leads when formed parallel.

ITEM	MILLIMETERS
A	10.16 MAX.
B	1.27 MAX.
C	2.54 (T.P.)
D	0.50±0.10
F	1.4 MIN.
G	3.2±0.3
H	0.51 MIN.
I	4.31 MAX.
J	5.08 MAX.
K	7.62 (T.P.)
L	6.4
M	0.25 <sup>+0.10</sup> <sub>-0.05</sub>
N	0.25
P	0.9 MIN.
R	0~15°

P8C-100-300B,C-2

8-PIN PLASTIC SOP (5.72 mm (225))



**NOTE**

Each lead centerline is located within 0.12 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
A	5.2 <sup>+0.17</sup> / <sub>-0.20</sub>
B	0.78 MAX.
C	1.27 (T.P.)
D	0.42 <sup>+0.08</sup> / <sub>-0.07</sub>
E	0.1±0.1
F	1.59±0.21
G	1.49
H	6.5±0.3
I	4.4±0.15
J	1.1±0.2
K	0.17 <sup>+0.08</sup> / <sub>-0.07</sub>
L	0.6±0.2
M	0.12
N	0.10
P	3° <sup>+7°</sup> / <sub>-3°</sub>

S8GM-50-225B-6

★ RECOMMENDED SOLDERING CONDITIONS

When soldering this product, it is highly recommended to observe the conditions as shown below. If other soldering processes are used, or if the soldering is performed under different conditions, please make sure to consult with our sales offices.

For more details, refer to our document "SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL"(C10535E).

Type of Surface Mount Device

μPC4556G2: 8-pin plastic SOP (5.72 mm (225))

Process	Conditions	Symbol
Infrared Ray Reflow	Peak temperature: 235°C or below (Package surface temperature), Reflow time: 30 seconds or less (at 210°C or higher), Maximum number of reflow processes: 3 time.	IR35-00-3
Vapor Phase Soldering	Peak temperature: 215°C or below (Package surface temperature), Reflow time: 40 seconds or less (at 200°C or higher), Maximum number of reflow processes: 3 time.	VP15-00-3
Wave Soldering	Solder temperature: 260°C or below, Flow time: 10 seconds or less, Maximum number of flow processes: 1 time, Pre-heating temperature: 120°C or below (Package surface temperature).	WS60-00-1
Partial Heating Method	Pin temperature: 300°C or below, Heat time: 3 seconds or less (Per each side of the device).	—

**Caution** Apply only one kind of soldering condition to a device, except for "partial heating method", or the device will be damaged by heat stress.

Type of Through-hole Device

μPC4556C: 8-pin plastic DIP (7.62 mm (300))

Process	Conditions
Wave Soldering (only to leads)	Solder temperature: 260°C or below, Flow time: 10 seconds or less.
Partial Heating Method	Pin temperature: 300°C or below, Heat time: 3 seconds or less (per each lead).

**Caution** For through-hole device, the wave soldering process must be applied only to leads, and make sure that the package body does not get jet soldered.

[MEMO]

[MEMO]

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